L Number	Hits	Search Text	DB	Time stamp
-	0	"sputtering target" and grain and ".mu."$	USPAT; EPO; JPO; DERWENT	2002/03/04 09:55
-	715	"sputtering target" and grain	USPAT; EPO; JPO; DERWENT	2001/02/28 13:23
-	539	"sputtering target" and grain and size	USPAT; EPO; JPO; DERWENT	2001/02/28 13:24
-	73	("sputtering target" and grain and size) and (cast casting)	USPAT; EPO; JPO; DERWENT	2001/02/28 13:24
-	0	(("sputtering target" and grain and size) and (cast casting)) and homogenous	USPAT; EPO; JPO; DERWENT	2001/02/28 13:24
-	7	(("sputtering target" and grain and size) and (cast casting)) and precipitates	USPAT; EPO; JPO; DERWENT	2001/02/28 13:25
-	12	(("sputtering target" and grain and size) and (cast casting)) and precipitate	USPAT; EPO; JPO; DERWENT	2001/02/28 13:25
-	2	5590389.pn. or 5780755.pn.	USPAT	2001/07/24 16:16
-	4	"08100255" "08064554"	JPO; DERWENT	2001/02/28 15:34
-	3668	"sputtering target"	JPO; DERWENT	2001/02/28 15:34
-	6395	"sputtering target"	USPAT; EPO; JPO; DERWENT	2001/02/28 15:35
-	715	"sputtering target" and grain	USPAT; EPO; JPO; DERWENT	2001/02/28 15:36
-	539	("sputtering target" and grain) and size	USPAT; EPO; JPO; DERWENT	2001/02/28 15:36
-	247	(("sputtering target" and grain) and size) and uniform	USPAT; EPO; JPO; DERWENT	2001/02/28 15:36
-	821	"sputtering target" and grain	USPAT; EPO; JPO; DERWENT	2001/02/28 15:36
-	604	("sputtering target" and grain) and size	USPAT; EPO; JPO; DERWENT	2001/02/28 15:36
-	280	(("sputtering target" and grain) and size) and uniform	USPAT; EPO; JPO; DERWENT	2001/02/28 15:37
-	338	(("sputtering target" and grain) and size) and uniform$5	USPAT; EPO; JPO; DERWENT	2001/02/28 15:37
-	4	((("sputtering target" and grain) and size) and uniform$5) and homogenous	USPAT; EPO; JPO; DERWENT	2001/02/28 15:41
-	188	((("sputtering target" and grain) and size) and uniform$5) not magnet$	USPAT; EPO; JPO; DERWENT	2001/02/28 15:42
-	172	(((("sputtering target" and grain) and size) and uniform$5) not magnet$) not record$	USPAT; EPO; JPO; DERWENT	2001/03/01 09:03
-	188	(((("sputtering target" and grain) and size) and uniform$5) not magnet$) not record$	USPAT; EPO; JPO; DERWENT	2001/03/01 09:06
-	135	(((("sputtering target" and grain) and size) and uniform$5) not magnet$4) not record$4	USPAT; EPO; JPO; DERWENT	2001/03/01 09:07
-	12	420/529.ccls. and sputter$	USPAT; EPO; JPO; DERWENT	2001/03/01 14:00
-	6395	"sputtering target"	USPAT; EPO; JPO; DERWENT	2001/03/02 10:19

-	8068	"sputtering target" or "target sputtering"	USPAT; EPO; JPO; DERWENT	2001/03/02 10:19
-	3699	("sputtering target" or "target sputtering") and (al aluminum)	USPAT; EPO; JPO; DERWENT	2001/03/02 10:20
-	1206	(("sputtering target" or "target sputtering") and (al aluminum)) and (copper)	USPAT; EPO; JPO; DERWENT	2001/03/02 10:20
-	1633	(("sputtering target" or "target sputtering") and (al aluminum)) and (copper cu)	USPAT; EPO; JPO; DERWENT	2001/03/02 10:20
-	673	((("sputtering target" or "target sputtering") and (al aluminum)) and (copper cu)) and (texture textured orient oriented orientation orientated)	USPAT; EPO; JPO; DERWENT	2001/03/02 10:21
-.	194	(((("sputtering target" or "target sputtering") and (al aluminum)) and (copper cu)) and (texture textured orient oriented orientation orientated)) and grain	USPAT; EPO; JPO; DERWENT	2001/03/02 10:21
-	107	((((("sputtering target" or "target sputtering") and (al aluminum)) and (copper cu)) and (texture textured orient oriented orientation orientated)) and grain) and (homogenous uniform)	USPAT; EPO; JPO; DERWENT	2001/03/02 10:22
-	46	(((((("sputtering target" or "target sputtering") and (al aluminum)) and (copper cu)) and (texture textured orient oriented orientation orientated)) and grain) and (homogenous uniform)) and (micron $".mu.m")	USPAT; EPO; JPO; DERWENT	2001/03/02 10:23
-	16	(equal adj channel adj angular adj extru$4) or ecae	USPAT; EPO; JPO; DERWENT	2001/07/24 14:16
-	6	sputtering adj target and grain and homogenous and texture	USPAT; EPO; JPO; DERWENT	2001/07/24 15:47
-	93	atomization and alloy and homogenous	USPAT	2001/07/24 16:21
-	1	atomization with alloy with homogenous	USPAT	2001/07/24 16:27
-	49	atomization same homogenous	USPAT	2001/07/24 16:27
-	21	atomization with homogenous	USPAT	2001/07/24 16:27
-	5	5590389.pn. or 5780755.pn.	USPAT; EPO; JPO; DERWENT	2001/07/24 17:04
-	1451	sputtering adj target and (ni! nickel "ni:")	USPAT; EPO; JPO; DERWENT	2001/07/24 17:05
-	962	sputtering adj target and (ag! silver "ag:")	USPAT; EPO; JPO; DERWENT	2001/07/24 17:05
-	11	sputtering adj target and (ni! nickel "ni:") and atomization	USPAT; EPO; JPO; DERWENT	2001/07/24 17:05
-	3	(sputtering adj target and (ni! nickel "ni:") and atomization) and (sputtering adj target and (ag! silver "ag:") and atomization)	USPAT; EPO; JPO; DERWENT	2001/07/24 17:07
-	15	(sputtering adj target and (ni! nickel "ni:") and atomization) or (sputtering adj target and (ag! silver "ag:") and atomization) not ((sputtering adj target and (ni! nickel "ni:") and atomization) and (sputtering adj target and (ag! silver "ag:") and atomization))	USPAT; EPO; JPO; DERWENT	2001/07/24 17:07
-	7	sputtering adj target and (ag! silver "ag:") and atomization	USPAT; EPO; JPO; DERWENT	2001/07/24 17:12

-	520	sputtering adj target and (ag! silver "ag:") and (ni! "ni:" nickel)	USPAT; EPO; JPO; DERWENT	2001/07/24 17:12
-	141	(sputtering adj target and (ag! silver "ag:") and (ni! "ni:" nickel)) and grain	USPAT; EPO; JPO; DERWENT	2001/07/24 17:12
-	127	((sputtering adj target and (ag! silver "ag:") and (ni! "ni:" nickel)) and grain) and alloy	USPAT; EPO; JPO; DERWENT	2001/07/24 17:12
-	43	sputtering adj target same (ni! "ni:" nickel) same (ag! "ag:" silver)	USPAT; EPO; JPO; DERWENT	2001/07/25 08:50
-	28	sputtering adj target and (copper cu) near (base based balance rest remainder) and (au gold ag silver)	USPAT; EPO; JPO; DERWENT	2002/03/04 10:00
-	26	sputtering adj target and (copper cu) near (base based balance rest remainder) and (ag silver)	USPAT; EPO; JPO; DERWENT	2002/03/04 10:00
-	8	sputtering adj target and (copper cu) near (base based balance rest remainder) same (ag silver)	USPAT; EPO; JPO; DERWENT	2002/03/04 10:00
-	6	precipitate same (sputter$3 near target) same coat$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 12:12
-	63	precipitate same (sputter$3 near target)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 12:12
-	57	(precipitate same (sputter$3 near target)) not (precipitate same (sputter$3 near target) same coat$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 12:19
-	0	precipitat$3 with splatter$3 and sputter$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 12:20
-	672	precipitat$3 with coat$3 and sputter$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 12:20
-	43	precipitat$3 with coat$3 with (effect affect) and sputter$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 12:23
-	19	wilkins.xa. and sputter$3	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 12:27
-	2	5826456.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/05/08 12:44